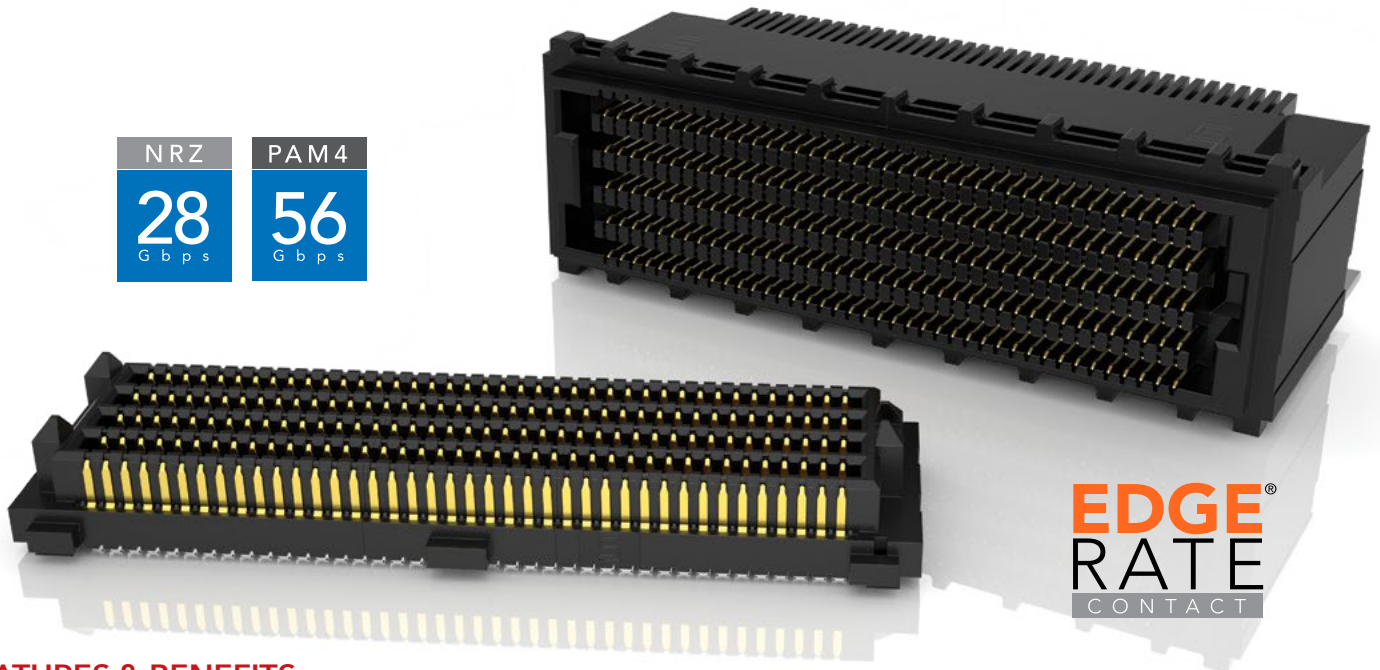


SEARAY™ .8mm

ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

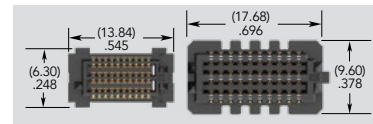
(0.80 mm) .0315" PITCH



NRZ	PAM4
28 Gbps	56 Gbps

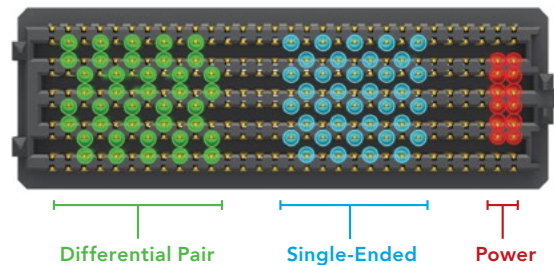
FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate® contact system
- Up to 500 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces



0.80 mm pitch vs. 1.27 mm pitch
(60 pins shown)

MAXIMUM GROUNDING & ROUTING FLEXIBILITY




KEY SPECIFICATIONS

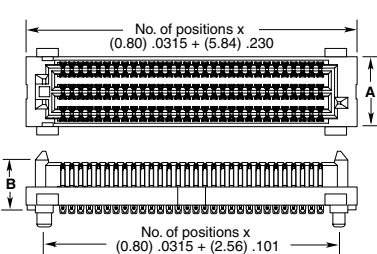
PITCH	STACK HEIGHTS	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	LEAD-FREE SOLDERABLE
0.80 mm	7 mm & 10 mm	up to 500 I/Os	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	1.3 A per pin (10 adjacent pins powered)	Yes

(0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS

SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X"R
SEAM8 Terminal	-10, -20, -30, -40, -50	-S02.0 = 2 mm Body Height (SEAM8 only)	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04	-1 = Tin/Lead Alloy Solder Crimp (-STL only)	-GP = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	Tape & Reel is standard. Leave blank for Tape & Reel.
		-S05.0 = 5 mm Body Height (SEAM8 only)	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-06			
SEAF8 Socket	-10, -20, -30, -40, -50	-S05.0 = 5 mm Body Height (SEAM8 only)	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08	-3 = Lead-Free Solder Crimp	-GP = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
		-05.0 = 5 mm Body Height (SEAF8 only)	-STL = 30 μ" (0.76 μm) Gold on contact, Matte Tin/Lead on solder tail (-1 solder type only)	-10			

SEAM8
Board Mates:
SEAF8
Cable Mates:
ESCA
Standoffs:
JSO






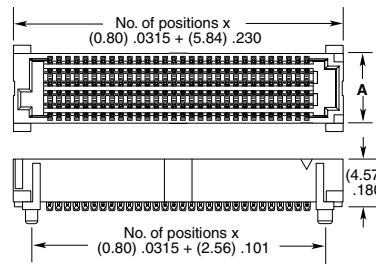
No. of positions x
(0.80) .0315 + (5.84) .230

No. of positions x
(0.80) .0315 + (2.56) .101

LEAD STYLE	B
-S02.0	(4.54) .179
-S05.0	(7.54) .297

NO. OF ROWS	A
-04	(4.30) .169
-06	(6.30) .248
-08	(8.30) .327
-10	(10.30) .406

SEAF8
Board Mates:
SEAM8
Cable Mates:
ESCA
Standoffs:
JSO


MATED HEIGHTS*		
SEAF8 LEAD STYLE	SEAM8 LEAD STYLE	
	-S02.0	-S05.0
-05.0	(7.00) .276	(10.00) .394

*Processing conditions will affect mated height.

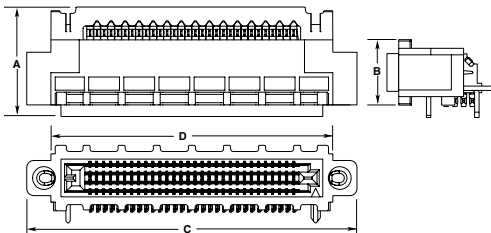
Note:
Polyimide Pick & Place Pad
standard without specifying -K.

SEAF8	NO. PINS PER ROW	1	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
SEAF8-RA (Right-angle)	-20, -30, -40, -50	1	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04	-2 = Lead-Free Solder Crimp	-GP = Guide Post Holes	-GP = Guide Post Holes	Tape & Reel is standard. Leave blank for Tape & Reel.
				-08				
				-10				

SEAF8-RA
(Right-angle)
Board Mates:
SEAM8
Cable Mates:
ESCA



NO. OF ROWS	A	B
-04	(12.48) .491	(7.46) .294
-08	(16.48) .649	(11.46) .451
-10	(18.48) .728	(13.46) .530



NO. PINS PER ROW	C	D
-20	(29.62) 1.166	(24.12) .950
-30	(37.62) 1.481	(32.12) 1.265
-40	(45.62) 1.796	(40.12) 1.580
-50	(53.62) 2.111	(48.12) 1.894

Notes:
Some sizes, styles and
options are non-standard,
non-returnable